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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of

Applicant : Nishimura Tetsuro
Serial No. : 09/450,632
Filed : November 24, 1999
Title : LEAD-FREE SOLDER-ALLOY
Docket : 550718-070
Art Unit : 1742

BOX NON-FEE AMENDMENT
Assistant Commissioner of Patents
Washington, D.C. 20231

Sir:

SECOND PRELIMINARY AMENDMENT

Prior to examination, please amend the above-identified application as follow:

IN THE CLAIMS:

Please cancel claims 4, ~~5~~, and 6; and add the following new claims 7-15:

- B¹ c 4-7. A lead-free solder alloy according to claim 1 wherein Ni is added to a ~~solder~~
base alloy of Sn-Cu.
- 5x. A lead-free solder alloy according to claim 2 wherein Ni is added to a ~~solder~~
base alloy of Sn-Cu.

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